

Abstract

**METHOD FOR CONNECTING AN INTEGRATED CIRCUIT TO A  
SUBSTRATE AND CORRESPONDING CIRCUIT ARRANGEMENT**

An integrated circuit, in particular from a chip, a wafer or a hybrid, to a substrate. A package is provided for the integrated circuit, which has a connection side, on which there are provided a plurality of connection regions for connection to the substrate. A corresponding plurality of connection regions are provided on the substrate, and elevated contact regions are provided on the connection regions of the package and/or the connection regions of the substrate. The elevated contact regions include a first group of contact regions and a second group of contact regions. A connection of the package to the substrate is created via the elevated contact regions. The elevated contact regions configured such that the first group of contact regions form a rigid connection and the second group of contact regions form an elastic connection between the package and the substrate. The invention likewise provides a corresponding circuit arrangement.

## List of reference symbols

	100	Circuit substrate
	20	Encapsulation
5	110,150,	
	140,150'	Connection regions
	7	Lines
	8	Adhesive composition
	AS	Connection side
10	VS	Front side
	RS	Rear side
	5	Chip
	10	Adhesive layer
	15	Interposer
15	30	Solder balls
	35	Plastic elements
	6	Contact pads
	38	Metalization
	IR	Near region
20	OR	Far region
	1a,1b,	
	1a',1b',	
	1c'	Package including chip
	NP	Neutral point
25	ST	Stress
	V	Flexure effect
	39	Solder
	150''	Interconnect
	25	Dielectric
30	120 s	Solder resist layer